# ADVANCED POWER **TECHNOLOGY**

### APT12040JLL

**1000V 24A 0.400**Ω

## POWER MOS 7™

Power MOS 7<sup>™</sup> is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7™ by significantly lowering R<sub>DS(ON)</sub> and Q<sub>a</sub>. Power MOS 7<sup>™</sup> combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with APT's patented metal gate structure.



Increased Power Dissipation

Lower Miller Capacitance

Easier To Drive

Lower Gate Charge, Qg







#### **MAXIMUM RATINGS**

All Ratings:  $T_C = 25^{\circ}$ C unless otherwise specified.

Symbol	Parameter	APT12040JLL	UNIT	
V <sub>DSS</sub>	Drain-Source Voltage	1200	Volts	
I <sub>D</sub>	Continuous Drain Current @ T <sub>C</sub> = 25°C	24	Amno	
I <sub>DM</sub>	Pulsed Drain Current ①	96	Amps	
V <sub>GS</sub>	Gate-Source Voltage Continuous	±30	Valta	
V <sub>GSM</sub>	Gate-Source Voltage Transient	±40	Volts	
P <sub>D</sub>	Total Power Dissipation @ T <sub>C</sub> = 25°C	595	Watts	
' D	Linear Derating Factor	4.76	W/°C	
$T_J, T_STG$	Operating and Storage Junction Temperature Range	-55 to 150	°C	
T <sub>L</sub>	Lead Temperature: 0.063" from Case for 10 Sec.	300		
I <sub>AR</sub>	Avalanche Current (Repetitive and Non-Repetitive)	22	Amps	
E <sub>AR</sub>	Repetitive Avalanche Energy ①	50	m	
E <sub>AS</sub>	Single Pulse Avalanche Energy 4	3200	mJ	

#### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage (V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA)	1200			Volts
I <sub>D(on)</sub>	On State Drain Current $@$ ( $V_{DS} > I_{D(on)} \times R_{DS(on)} Max, V_{GS} = 10V$ )	24			Amps
R <sub>DS(on)</sub>	Drain-Source On-State Resistance ② (V <sub>GS</sub> = 10V, 0.5 I <sub>D[Cont.]</sub> )			0.400	Ohms
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>DS</sub> = V <sub>DSS</sub> , V <sub>GS</sub> = 0V)			100	μA
	Zero Gate Voltage Drain Current $(V_{DS} = 0.8 V_{DSS}, V_{GS} = 0V, T_{C} = 125^{\circ}C)$			500	
I <sub>GSS</sub>	Gate-Source Leakage Current (V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V)			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage $(V_{DS} = V_{GS}, I_{D} = 5mA)$	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - http://www.advancedpower.com

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#### **DYNAMIC CHARACTERISTICS**

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Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V		8690		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V		1200		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1 MHz		908		
$Q_g$	Total Gate Charge <sup>③</sup>	V <sub>GS</sub> = 10V		306		
Q <sub>gs</sub>	Gate-Source Charge	$V_{DD} = 0.5 V_{DSS}$		37		nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	I <sub>D</sub> = I <sub>D[Cont.]</sub> @ 25°C		182		
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> = 15V		21		
t <sub>r</sub>	Rise Time	$V_{DD} = 0.5 V_{DSS}$		14		ns
t <sub>d(off)</sub>	Turn-off Delay Time	$I_{D} = I_{D[Cont.]} @ 25^{\circ}C$		67		113
t <sub>f</sub>	Fall Time	$R_G = 0.6\Omega$		24		

### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
Is	Continuous Source Current (Body Diode)			24	A
I <sub>SM</sub>	Pulsed Source Current (1) (Body Diode)			96	Amps
V <sub>SD</sub>	Diode Forward Voltage ② (V <sub>GS</sub> = 0V, I <sub>S</sub> = -I <sub>D[Cont.]</sub> )			1.3	Volts
t <sub>rr</sub>	Reverse Recovery Time $(I_S = -I_{D[Cont.]}, dI_S/dt = 100A/\mu s)$		1250		ns
Q rr	Reverse Recovery Charge $(I_S = -I_{D[Cont.]}, dI_S/dt = 100A/\mu s)$		31.0		μC
dv/ <sub>dt</sub>	Peak Diode Recovery dv/ <sub>dt</sub> ⑤			10	V/ns

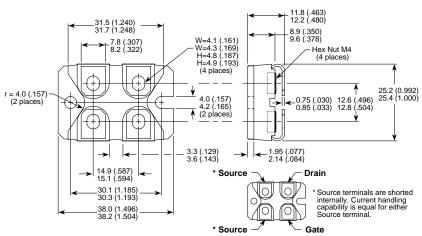
#### THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{ hetaJC}$	Junction to Case			0.21	°C/W
$R_{ hetaJA}$	Junction to Ambient			40	C/VV

<sup>1</sup> Repetitive Rating: Pulse width limited by maximum junction temperature.

APT Reserves the right to change, without notice, the specifications and information contained herein.

#### SOT-227 (ISOTOP®) Package Outline



Dimensions in Millimeters and (Inches)

<sup>2</sup> Pulse Test: Pulse width < 380 µs, Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

 $<sup>\</sup>textcircled{4}$  Starting T<sub>j</sub> = +25°C, L = 11.11mH, R<sub>G</sub> = 25 $\Omega$ , Peak I<sub>L</sub> = 24A 5 dv/<sub>dt</sub> numbers reflect the limitations of the test circuit rather than the device itself.  $I_S \le \neg I_{D[Cont.]}$   $di/_{dt} \le 700 \text{A/µs}$   $V_R \le V_{DSS}$   $T_J \le 150^{\circ}\text{C}$